



Product Change Notification / LIAL-02XWMF227

Date:

09-Jan-2023

Product Category:

Linear Comparators, Linear Op Amps, Power Management - System Supervisors/Voltage Detectors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5129 Final Notice: Qualification of G700 as a new molding compound material and NiPdAuAg with roughened as a new lead frame DAP surface prep for selected MIC7300, MIC2778, MIC833, and MIC2779 device families available in 5L SOT23 package assembled at STAR assembly site.

Affected CPNs:

[LIAL-02XWMF227_Affected_CPN_01092023.pdf](#)

[LIAL-02XWMF227_Affected_CPN_01092023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700 as a new molding compound material and NiPdAuAg with roughened as a new lead frame DAP surface prep for selected MIC7300, MIC2778, MIC833, and MIC2779 device families available in 5L SOT23 package assembled at STAR assembly site.

Pre and Post Change Summary:

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 05, 2022: Issued initial notification.

January 09, 2023: Issued final notification. Attached is the qualification report and added estimated first ship date by January 31,2023.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-02XWMF227_Qual Report.pdf](#)

[PCN_LIAL-02XWMF227_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC7300YM5-TR

MIC7300YM5-TX

MIC2778-1YM5-TR

MIC2778-2YM5-TR

MIC833YM5-TR

MIC2779H-1YM5-TR

MIC2779H-2YM5-TR

MIC2779L-1YM5-TR

MIC2779L-2YM5-TR